

## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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### Title of Invention

ENDPOINT DETECTION IN CHEMICAL-MECHANICAL  
POLISHING OF PATTERNED WAFERS HAVING A LOW PATTERN  
DENSITY

Application Number : 10/707120  
Confirmation Number:  
First Named Applicant: Xinhui Wang  
Attorney Docket Number: FIS920030031  
Art Unit: 3723  
Examiner:  
Search string: ( 6176765 or 6291351 or 6440263 ).pn

### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
DVN	1	6176765	2001-01-23	Li et al.			
I	2	6291351	2001-09-18	Li et al.			
↓	3	6440263	2002-08-27	Li et al.			

### Signature

Examiner Name	Date
<i>Dung van Nguyen</i>	8-9-2004